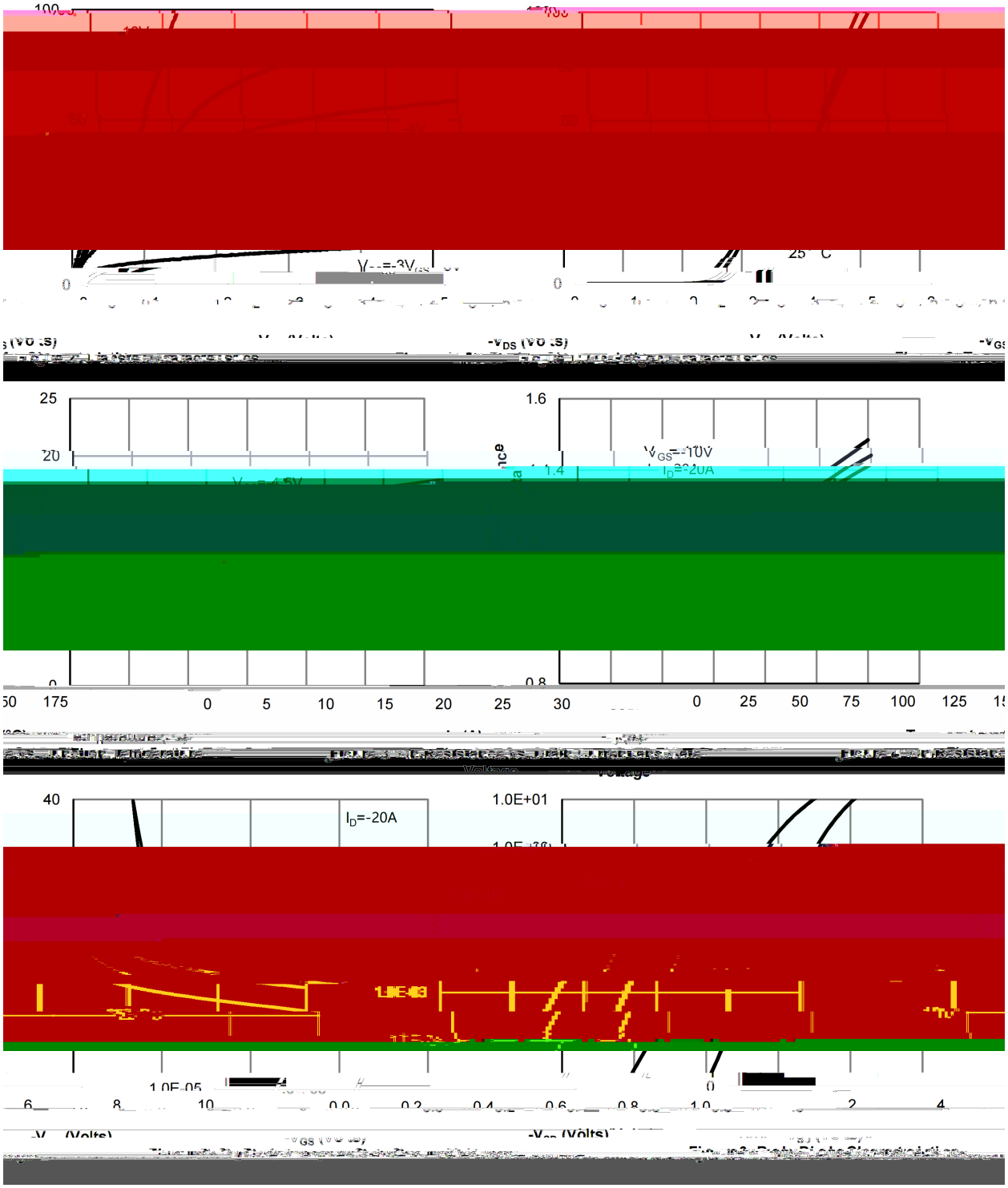
SGIQ6Ö6D0;0 ṂṂȽ S ڙ PRV ʆ ώ̰̃ Ẕ Ꞁ

Rev.A Nov.-2022

ν ῼ Parameter	ɣ ᴺ Symbol	╜ ꜝ ꞇ Test Conditions	ω ṇ Ӫ Min	Ɛ ʒ Ӫ Typ	ω ᶻ Ӫ Max	ᴅ ʮ Unit
Drain-Source Breakdown Voltage	BV_{DSS}	I_D=-250μA V_{GS}=0V	-30	-36		V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=-30V V_{GS}=0V			-1	μA
Gate-Body leakage current	I_{GSS}	V_{DS}=0V V_{GS}=±20V			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS} I_D=-250μA	-1.0	-1.7	-2.5	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	V_{GS}=-10V I_D=-20A		10.5	12	m
		V_{GS}=-4.5V I_D=-10A		16.5	18	
Diode Forward Voltage	V_{SD}	I_S=-1A V_{GS}=0V			-1.2	V
Gate resistance	R_g	V_{GS}=0V V_{DS}=0V f=1MHz		7.5	10	
Input Capacitance	C_{iss}	V_{GS}=0V V_{DS}=-25V f=1MHz		2100		pF
Output Capacitance	C_{oss}			340		
Reverse Transfer Capacitance	C_{rss}			210		
Total Gate Charge	Q_g(10V)	V_{GS}=-10V V_{DS}=-15V I_D=-17A		35		nC
Total Gate Charge	Q_g(4.5V)			17		
Gate-Source Charge	Q_{gs}			5.7		
Gate-Drain Charge	Q_{gd}			8.8		
Turn-on Delay Time	$t_{d(ON)}$	V_{GS}=-10V V_{DS}=-15V R_L=0.9Ω R_{GEN}=3Ω		11		ns
Turn-on Rise Time	t_r			7.5		
Turn-off Delay Time	$t_{d(OFF)}$			43.5		
Turn-off Fall Time	t_f			17.5		


25 C
25
20
1.6
1.4
0.8
0
5
10
15
20
25
30
0
25
50
75
100
125
40
I_D=-20A
1.0E+01
1.0E-05
0
2
4

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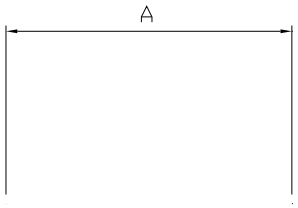
PDFN3X3A-8L

Unit:mm



Dimensions In Millimeterer
Symbol M

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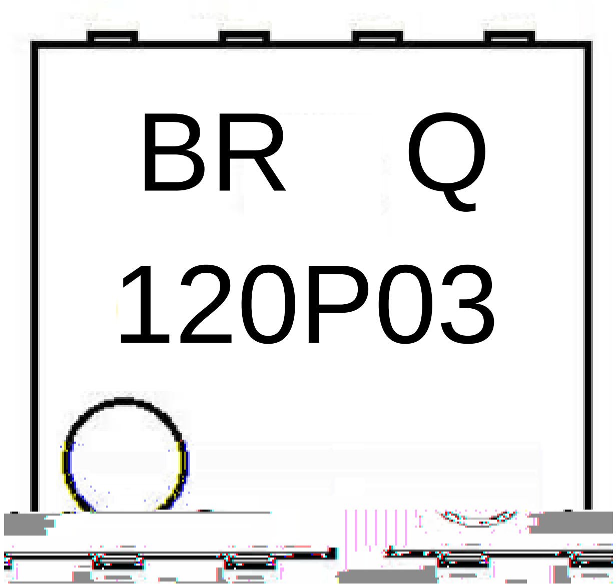

ب ˝ χ

BR χ ㅒ ʒ ᴻ ჩ

120P03 χ ㅒ ʒ ᴺ ჩ

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Note:

BR: Company Code

120P03: Product Type Code

****: Lot No. Code, code change with Lot No

Temperature Profile for IR Reflow Soldering(Pb-Free)

ب ˝ χ

1 Ĺ ♬ □ ỷ 150 Ḱ 200 ɬ ı `H ڑ 60 Ḱ 120sec;

2 Š Ө □ ỷ 255 ° 5 ɬ ı `H ڑ 'Y ʌ ʁ 5 ° 0.5sec;

3 ì ˙ ٢ ˛ ɔ ♣ ỷ ʁ 2 Ḱ 10 ɬ /sec.

Note:

1.Preheating:150~200 ɬ , Time:60~120sec.

2.Peak Temp.:255 ° 5 ɬ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɬ /sec.

□ ỷ χ 260 ° 5 ɬ `H ڑ χ 10 ° 1 sec. Temp.:260 ° 5 ɬ Time:10 ° 1 sec

ɔ ` ɣ Ł / REEL

Package Type	Units	Dimension	(unit mm³)